

DISCO wafersaw tape mounter

-----Operation Guide

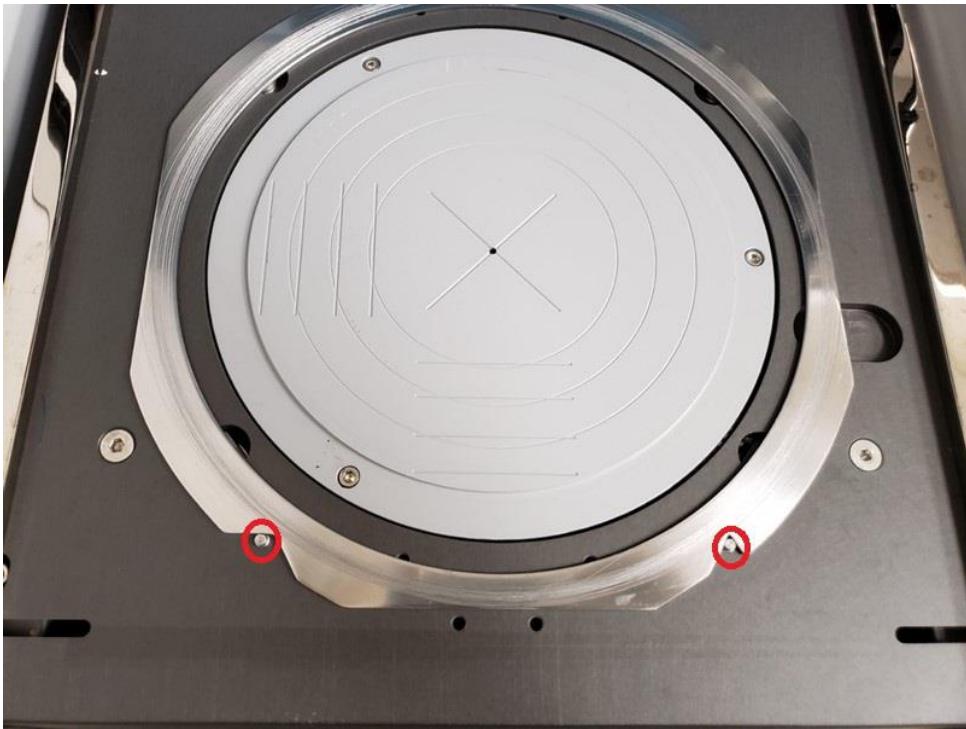
1. Begin by activating the vacuum pump. Switch is **red** and is located as seen in the image below(circled in **red**).



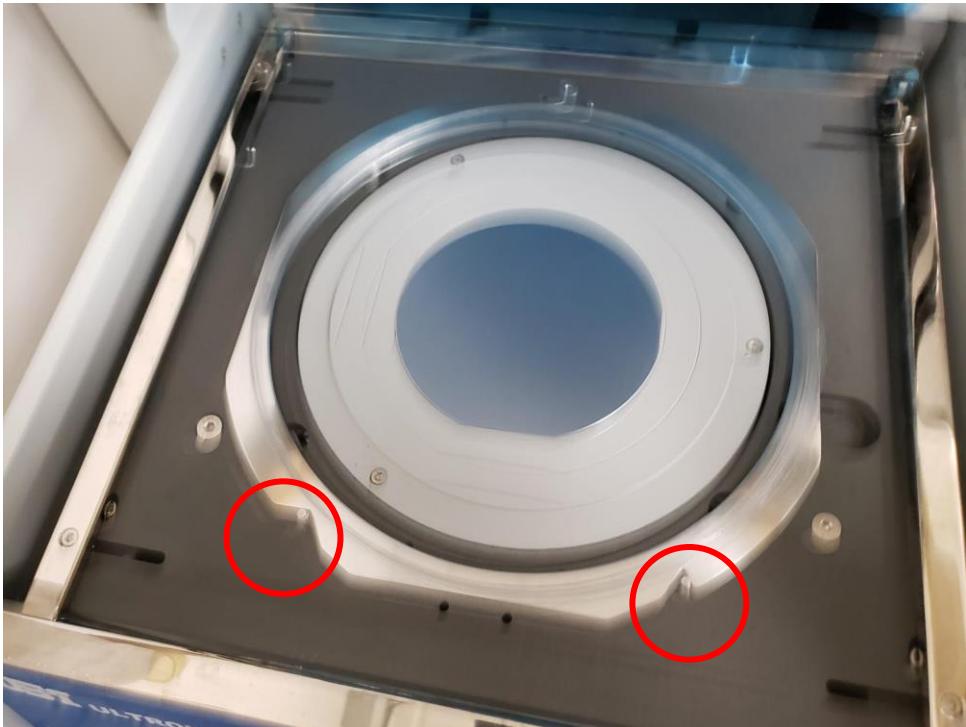
2. Turn on the machine using the orange power switch. Then, turn on the vacuum using the silver switch labelled “vacuum.”



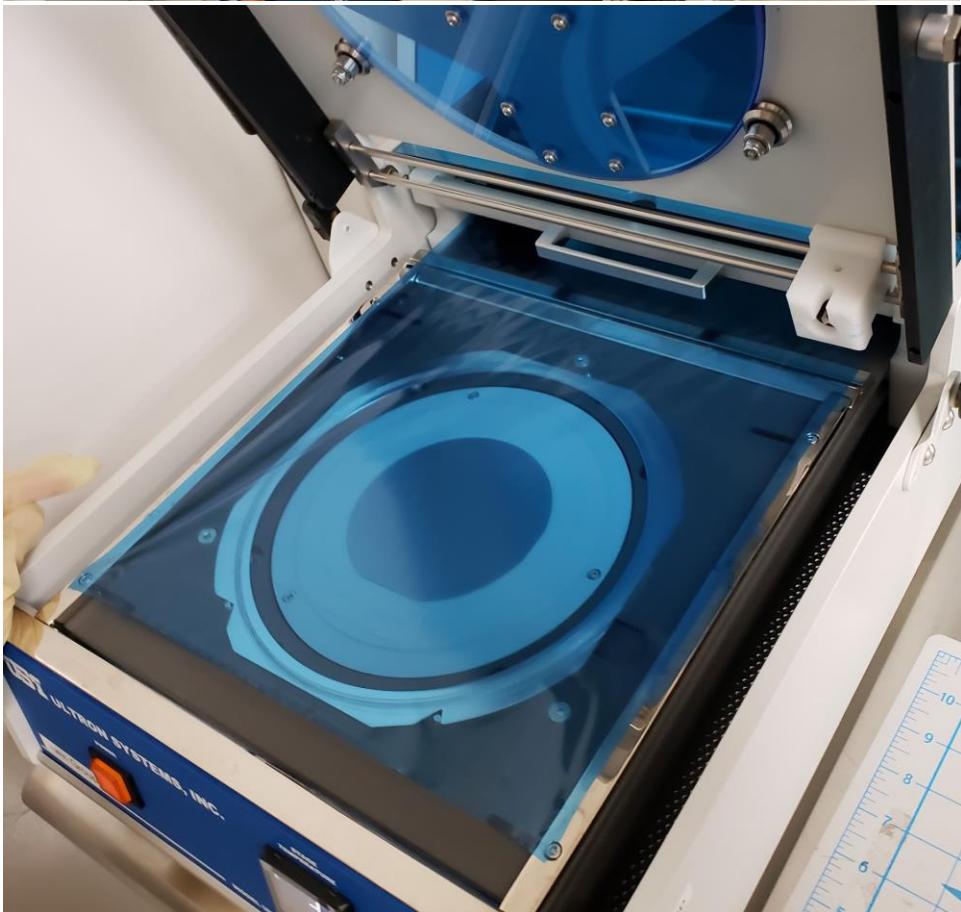
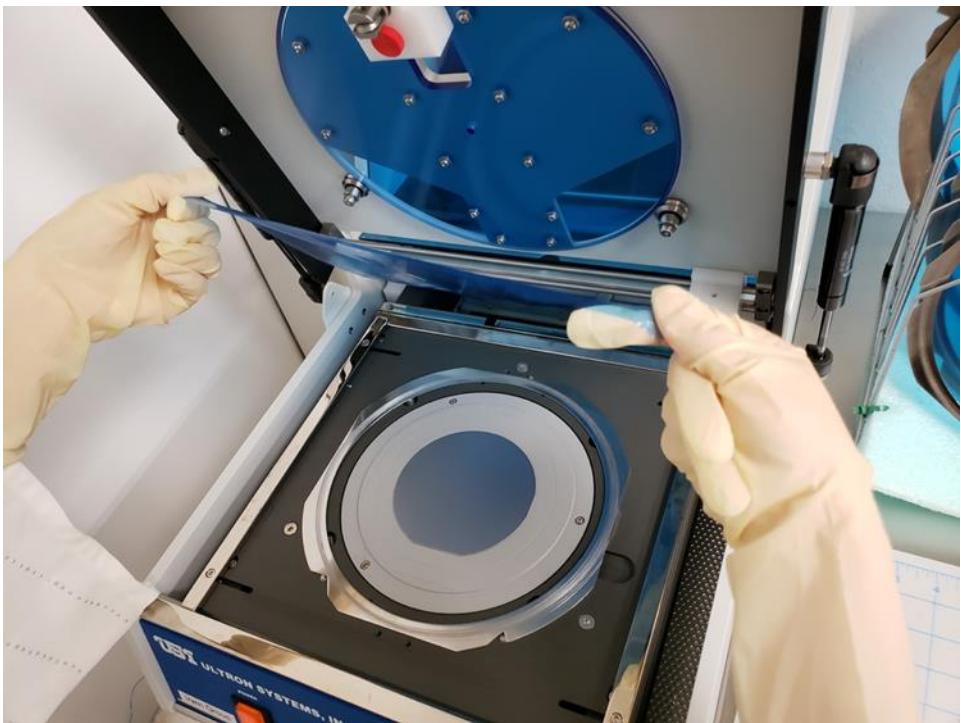
3. For best adhesion, **wait** until the stage temperature reaches the set point (50°).
4. Place the metal ring on the stage. Note the asymmetry of the metal ring, and the correct way this needs to be placed on the stage, where the two small metal pins are located (circled in **red**).



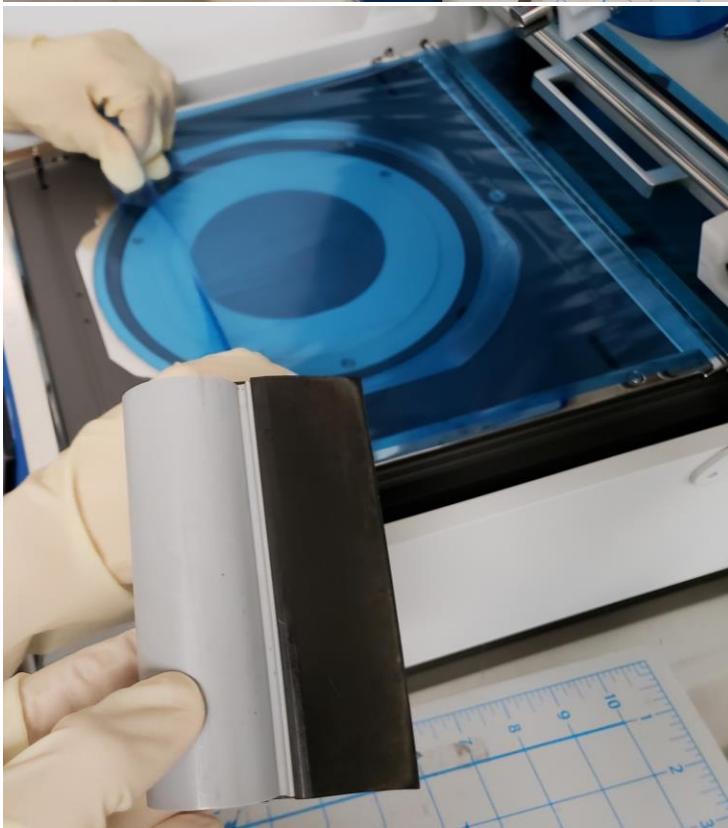
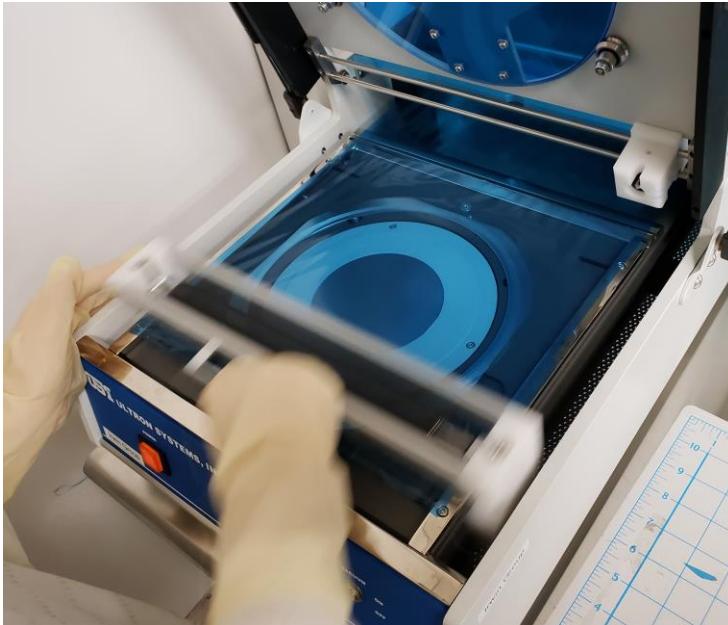
5. Place the wafer upside down on the center of the stage.



6. Pull out the tape and completely cover the wafer and the metal ring. Make sure the tape is affixed to the side rails.

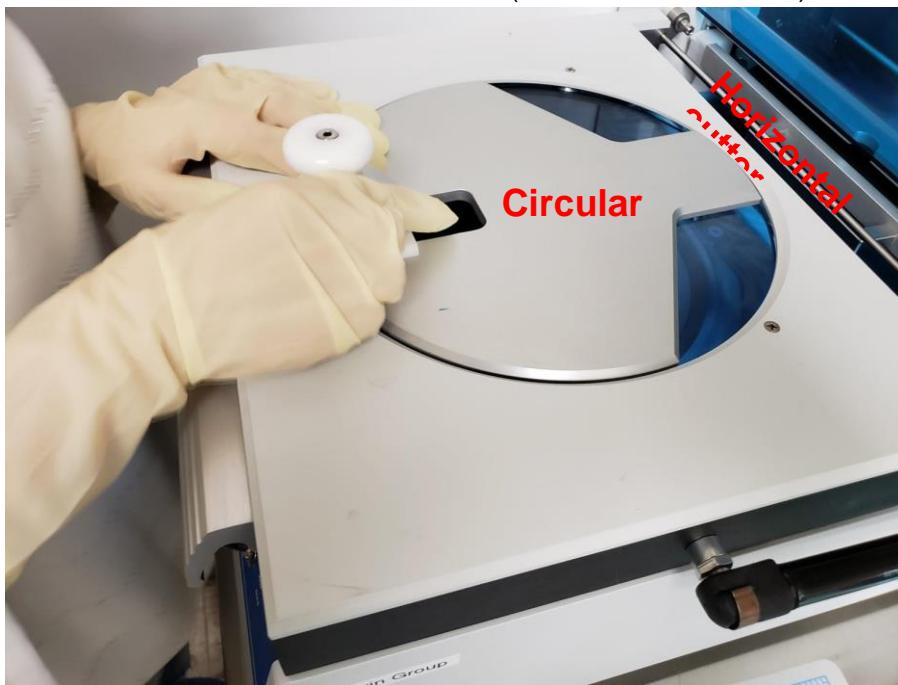


7. Pull out the roller tool and roll to smoothen out the tape and ensure proper adhesion to the backside of the wafer. If there are any bubbles present, remove them using the plastic smoothening hand tool.

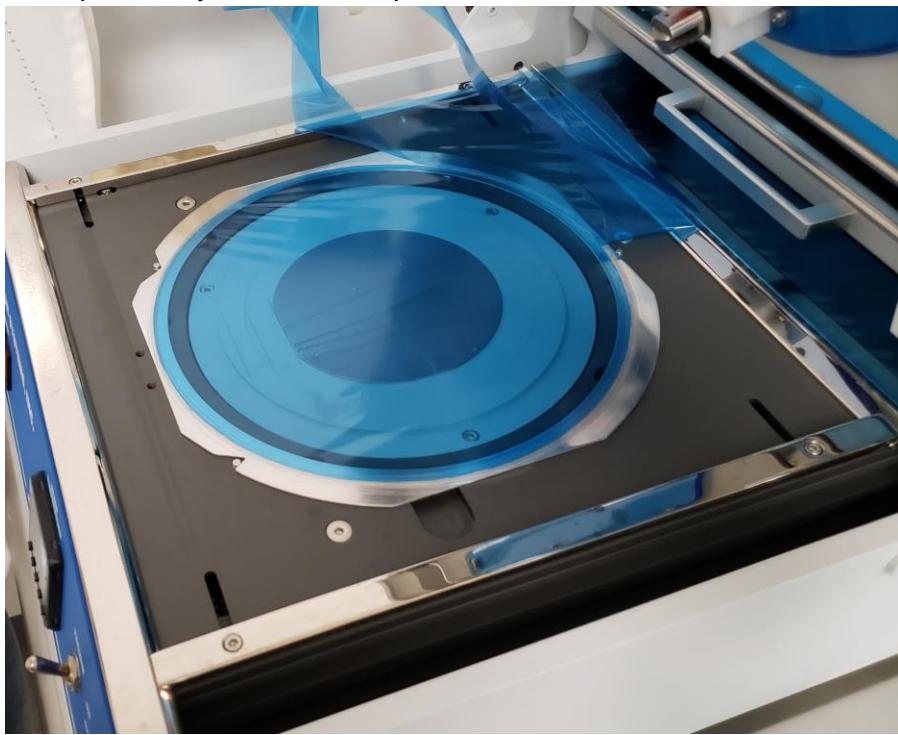


8. Close the lid. Using the horizontal cutter on top, make 3~4 cuts of the film by moving the cutter side to side: activate this cutter by pushing down on the black knob. Then, use

the circular cutter to make the final cut (make 3~4 revolutions).



9. Now, peel away the excess tape around the cuts made.



10. Turn everything off in opposite order (vacuum switch, orange power switch, vacuum pump).